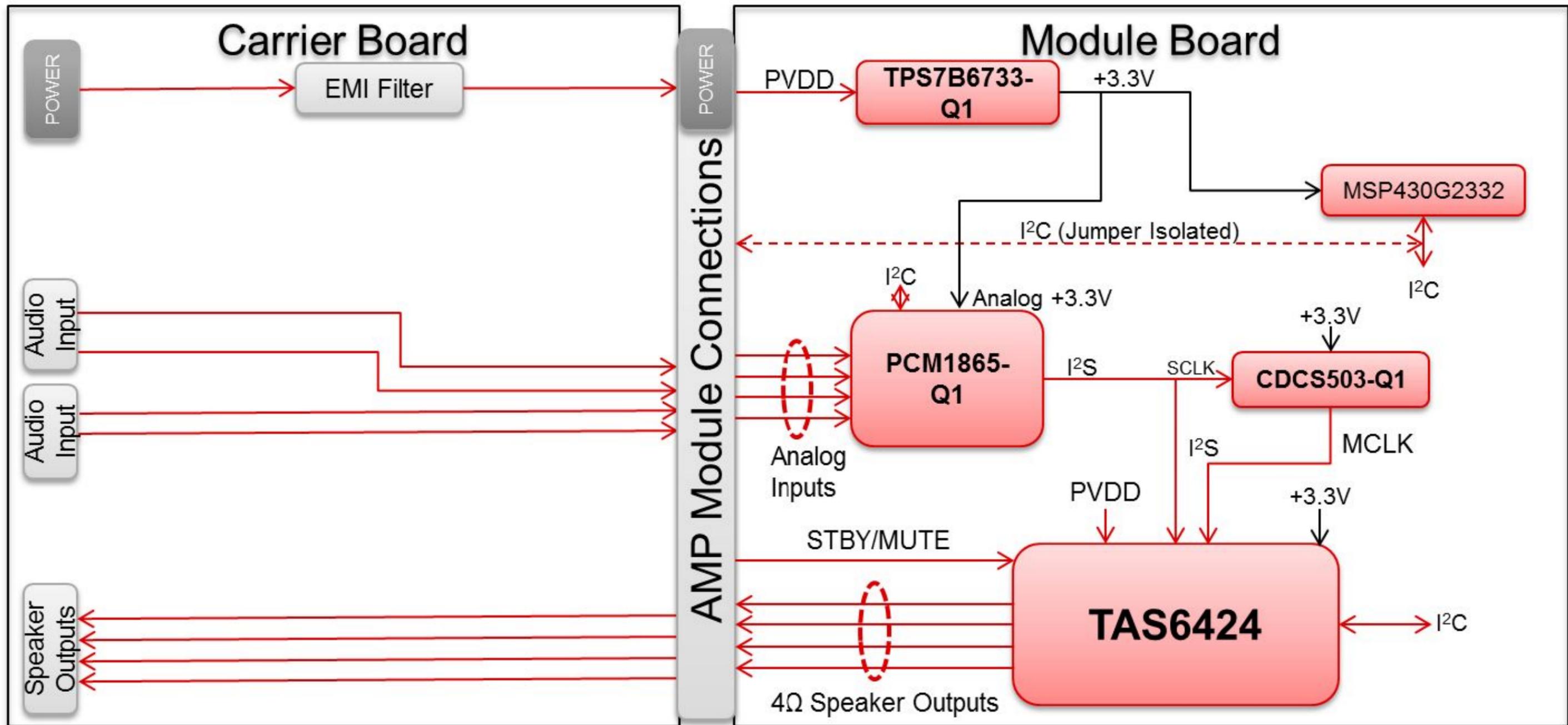


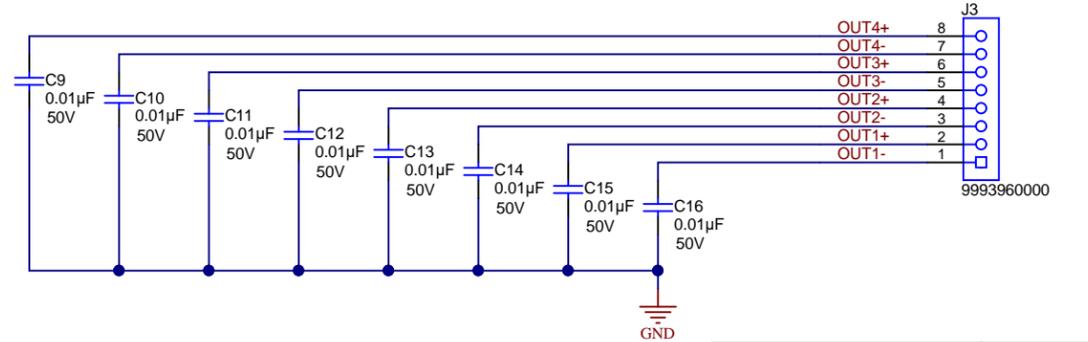
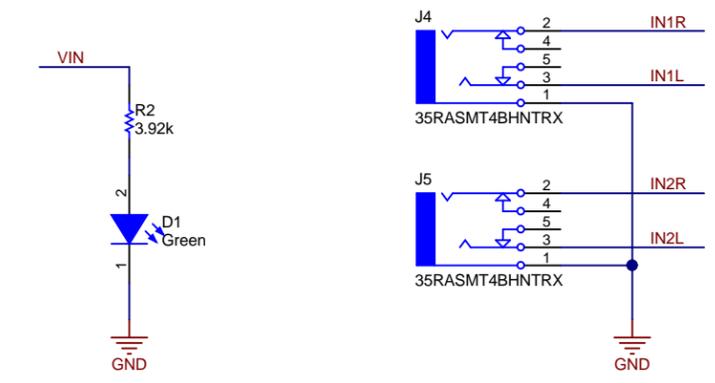
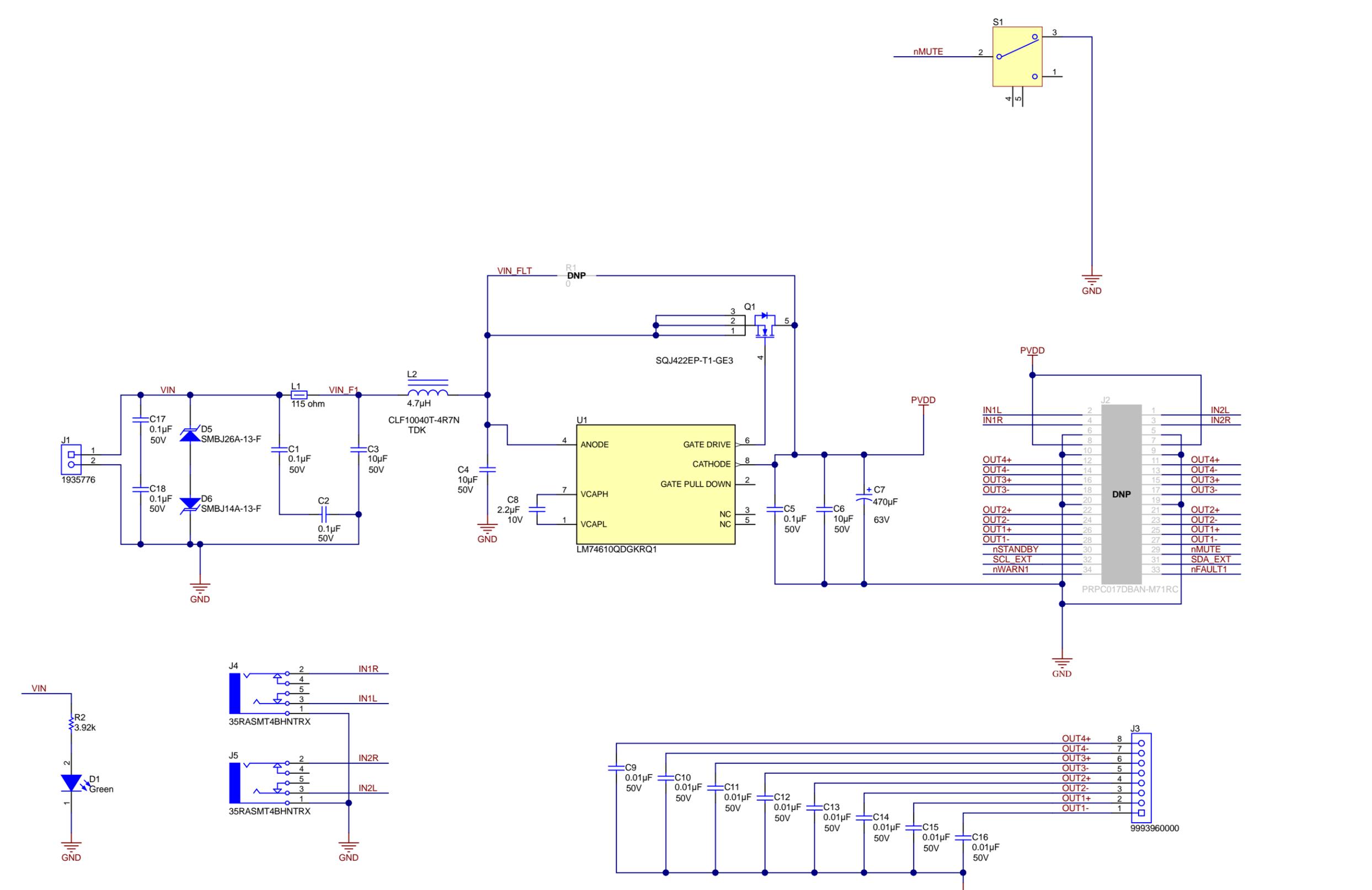
Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
B	N/A	05232017	N/A	Updated Inductor, changed power input layout



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TID #: <a href="#">TIDA-00743</a>	Project Title: <a href="#">Module Interface Board</a>	
Number: <a href="#">TIDA00743_2</a>   Rev: <a href="#">B</a>	Sheet Title:	
SVN Rev: <a href="#">Version control disabled</a>	Assembly Variant: <a href="#">001</a>	Sheet: <a href="#">1</a> of <a href="#">3</a>
Drawn By:	File: <a href="#">TIDA00743_2 Module Interface Sheet 1.SchDoc</a>	Size: <a href="#">B</a>
Engineer: <a href="#">M. Knapp</a>	Contact: <a href="#">http://www.ti.com/support</a>	

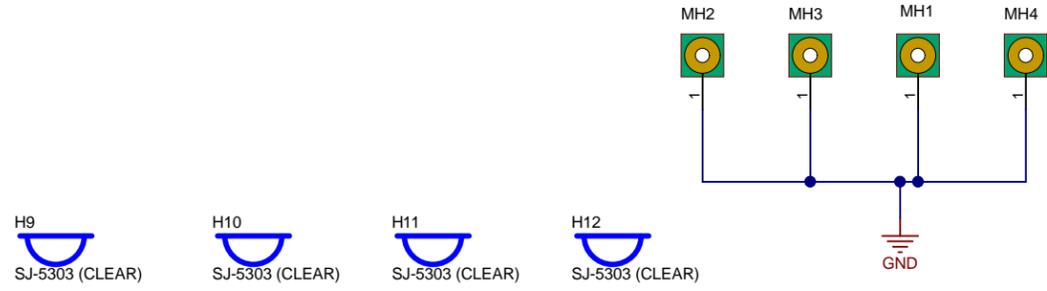




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TID #: TIDA-00743	Project Title: Module Interface Board	
Number: TIDA00743_2   Rev: B	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: TIDA00743_2 Module Interface Sheet 2.SchDoc	Size: B
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DNP FID1  
DNP FID2  
DNP FID3

PCB Number: TIDA00743\_2  
PCB Rev: B

PCB LOGO  
Pb-Free Symbol  
PCB LOGO  
FCC disclaimer

Label Table	
Variant	Label Text
001	Module Interface Board

ZZ1  
Label Assembly Note  
This Assembly Note is for PCB labels only

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ5  
Assembly Note  
Component L1 and L2 are Alternate parts. Only one or the other may be placed.

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TID #: <a href="#">TIDA-00743</a>	Project Title: <a href="#">Module Interface Board</a>	
Number: <a href="#">TIDA00743_2</a>   Rev: <a href="#">B</a>	Sheet Title:	
SVN Rev: <a href="#">Version control disabled</a>	Assembly Variant: <a href="#">001</a>	Sheet: <a href="#">3</a> of <a href="#">3</a>
Drawn By:	File: <a href="#">TIDA00743_2 Module Interface Sheet 3.SchDoc</a>	Size: <a href="#">B</a>
Engineer: <a href="#">M. Knapp</a>	Contact: <a href="#">http://www.ti.com/support</a>	

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